

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10595920			
<b>Filing Date:</b>	19-May-2006			
<b>Title of Invention:</b>	Photosensitive resin composition, photosensitive element, resist pattern forming method and process for manufacturing printed circuit board			
<b>First Named Inventor/Applicant Name:</b>	Ken Sawabe			
<b>Filer:</b>	Joerg-Uwe V. Szipl/Nichole Vasquez			
<b>Attorney Docket Number:</b>	SOEI0021			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	1615	2	50	100
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>910</b>